

HM11-11001LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (mg)	Composition (mg)
1	CORE	Rod Core	Iron	7439-89-6	15300	15147
			Binder	-		91.8
			Lubricant	-		61.2
2	ADHESIVE	Epoxy	Bisphenol F Epoxy Resin	9003-36-5	24.9	12.699
			Latent Hardener	Confidential		1.3446
			Hardener	461-58-5		0.7719
			Modified Epoxy Resin	Confidential		5.6025
			Sb ₂ O ₃	1309-64-4		1.1205
			CaCO ₃	471-34-1		2.4651
			Others	Confidential		0.8964
3	WIRE	Spring Coil	Copper (Cu)	7440-50-8	7000	6860
			Polyurethane (PU)	-		140
4	SOLDER	Lead Free Solder	Tin (Sn)	7440-31-5	10	6.5
			Silver (Ag)	7440-21-3		3
			Copper (Cu)	7440-50-8		0.5

Total Weight	22334.9
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